

Abstract

Adhesive Agent Composition, Layered Product and Production Method for Layered Product, and Method for Reducing Thickness of Semiconductor Forming Substrate

An adhesive composition for forming an adhesive layer that can bond a first substrate formed of a semiconductor-forming substrate to a second substrate formed of a support substrate in a peelable manner, the composition containing a component (A) which is cured through hydrosilylation and a peeling component (B) which contains a component containing an epoxy-modified polyorganosiloxane, wherein the component (A) contains a polysiloxane (A1) including a siloxane unit represented by SiO_2 (unit Q) and the like, and a platinum group metal catalyst (A2); and the polysiloxane (A1) contains a polyorganosiloxane (a1) including a siloxane unit represented by SiO_2 (unit Q') and the like, and a polyorganosiloxane (a2) including a siloxane unit represented by SiO_2 (unit Q'') and the like, and having a functional group (Si-H) content of 5.0 mol/kg or greater.

[No figure]